

L-Band Medium & High Power GaAs FET

FEATURES

• High Output Power: P_{1dB}=35.5dBm (Typ.)

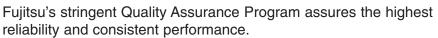
High Gain: G_{1dB}=11.5dB (Typ.)
High PAE: η_{add}=46% (Typ.)

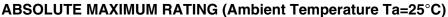
Proven Reliability

• Hermetically Sealed Package

DESCRIPTION

The FLL357ME is a Power GaAs FET that is specifically designed to provide high power at L-Band frequencies with gain, linearity and efficiency superior to that of silicon devices. The performance in multitone environments for Class AB operation make them ideally suited for base station applications. This device is assembled in hermetic metal/ceramic package.





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Item	Symbol Condition		Rating	Unit				
Drain-Source Voltage	VDS		15	V				
Gate-Source Voltage	VGS		-5	V				
Total Power Dissipation	P _{tot} T _C = 25°C		15	W				
Storage Temperature	T _{stg}		-65 to +175	°C				
Channel Temperature	T _{ch}		175	°C				

Fujitsu recommends the following conditions for the reliable operation of GaAs FETs:

1. The drain-source operating voltage (V_{DS}) should not exceed 10 volts.

ELECTRICAL CHARACTERISTICS (Ambient Temperature Ta=25°C)

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Item	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Saturated Drain Current	IDSS	V _{DS} = 5V, V _{GS} = 0V	-	1200	1800	mA	
Transconductance	9m	V _{DS} = 5V, I _{DS} = 800mA	-	600	-	mS	
Pinch-off Voltage	Vp	$V_{DS} = 5V$, $I_{DS} = 60$ mA	-1.0	-2.0	-3.5	V	
Gate Source Breakdown Voltage	VGSO	IGS = -60μA	-5	-	-	V	
Output Power at 1dB G.C.P.	P _{1dB}		34.5	35.5	-	dBm	
Power Gain at 1dB G.C.P.	G _{1dB}	V _{DS} = 10V I _{DS} ≈ 0.6I _{DSS} (Typ.), f = 2.3GHz	10.5	11.5	-	dB	
Power-added Efficiency	ηadd		-	46	-	%	
Thermal Resistance	R _{th}	Channel to Case	-	7.5	10	°C/W	

CASE STYLE: ME G.C.P.: Gain Compression Point



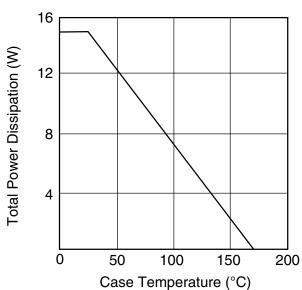
^{2.} The forward and reverse gate currents should not exceed 19.4 and -2.0 mA respectively with gate resistance of 100Ω .

^{3.} The operating channel temperature ($T_{\mbox{ch}}$) should not exceed 145°C.

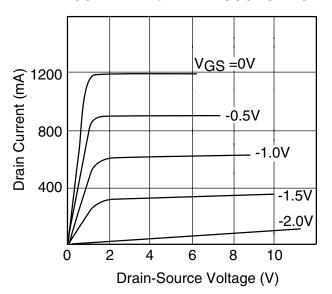
FLL357ME

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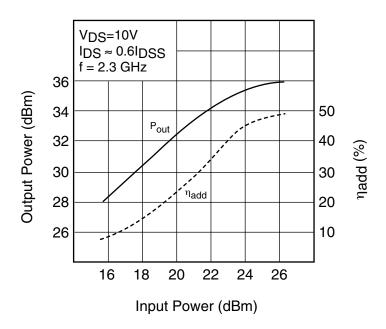
POWER DERATING CURVE



DRAIN CURRENT vs. DRAIN-SOURCE VOLTAGE



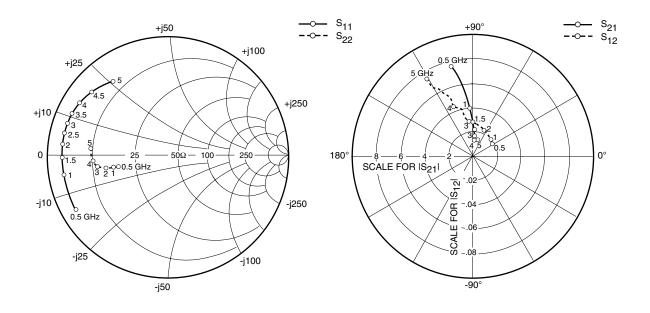
OUTPUT POWER vs. INPUT POWER





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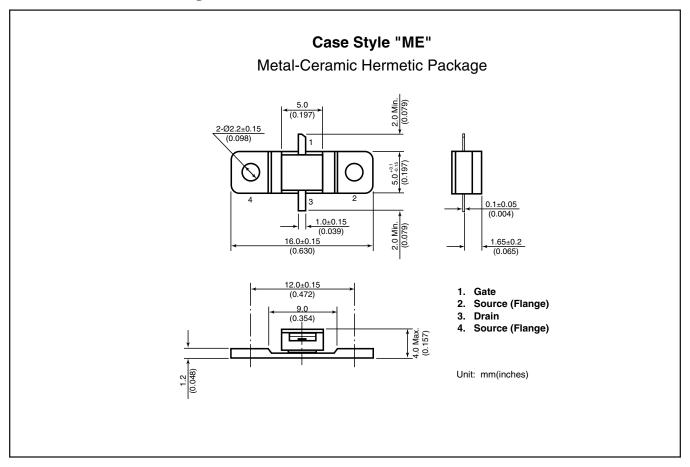
S-PARAMETERS

 $V_{DS} = 10V, I_{DS} = 720mA$

FREQUENCY	S11		S2	S21		S12		S22	
(MHZ)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG	
500	.890	-149.0	7.584	103.7	.019	30.4	.427	-167.0	
1000	.881	-169.3	3.963	94.3	.020	36.9	.461	-167.5	
1500	.883	-179.0	2.747	90.3	.022	50.9	.491	-168.0	
2000	.883	173.9	2.099	87.5	.023	64.9	.529	-168.1	
2500	.882	168.1	1.708	87.1	.027	81.5	.560	-168.9	
3000	.879	162.5	1.515	86.2	.028	94.6	.592	-170.5	
3500	.872	156.7	1.304	86.6	.039	103.3	.613	-172.9	
4000	.858	149.8	1.366	84.3	.044	111.8	.624	-175.1	
4500	.826	140.4	1.223	81.5	.052	111.2	.639	-179.1	
5000	.768	126.9	1.303	76.6	.074	120.7	.639	175.1	



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- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.

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